RoHS	
	Specification
	Client Name:
	Client P/N:
	Factory P/N:OF-SMD3528GL
	Sending Date:

Features

- •PLCC-2 Package.
- •Extremely wide viewing angle
- •Suitable for all SMT assembly and solder process
- Available on tape and reel
- Moisture sensitivity level: Level 4
- Package:2000pcs/reel
- RoHS compliant

Description

The Green source color devices are made with InGaN on Substrate Light Emitting Diode

Applications

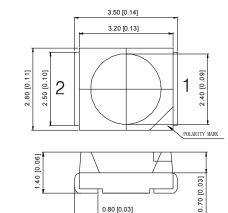
- Optical indicator
- Indoor display
- Backlighting in dashboard and switch
- ■Flat backlighting for LCD, symbol and display

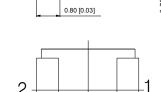
■General use

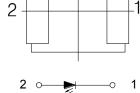
ATTENTION OBSERVE PRECAUTIONS

FOR HANDLING ELECTROSTATIC DISCHARGE SENSITIVE DEVICES

Package Dimensions





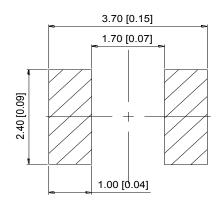


Notes:

1. All dimension units are millimeters.

2.All dimension tolerance is ±0.15mm unless otherwise noted.

Recommended Soldering Pattern



Selection Guide

Part No.	Dice	Lens Type	Luminous in @ 2	Viewing Angle	
			Min.	Тур.	2 0 1/2
OF-SMD3528GL	Green (InGaN)	Water Clear	600	780	120°

Note:

1. θ 1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value. 2.the above luminous intensity measurement allowance tolerance ±10%.

Electrical / Optical Characteristics at Ta=25°C

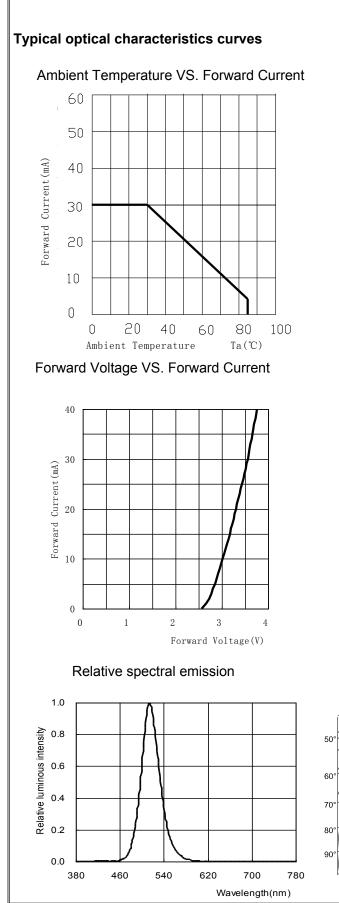
Parameter	Symbol	Min.	Тур.	Max	Units	Test Conditions
Forward Voltage	VF	2.8		3.4	V	I⊧=20mA
Reverse Current	lr			10	uA	VR = 5V
Dominate Wavelength	λd	512		522	nm	I⊧=20mA

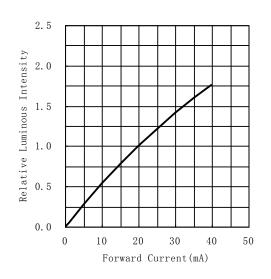
Absolute Maximum Ratings at Ta=25°C

Parameter	Symbol	Value	Units
Power dissipation	Pd	105	mW
DC Forward Current	lF	30	mA
Peak Forward Current [1]	İFP	100	mA
Reverse Voltage	VR	5	V
Electrostatic Discharge (HBM)	ESD	1000	V
Operating Temperature	Topr	-40 ~ +85	°C
Storage Temperature	Tstg	-40 ~ +100	°C

Note:

1.1/10 Duty Cycle, 0.1ms Pulse Width.2.The above forward voltage measurement allowance tolerance ±0.1V





Forward Current VS. Relative Intensity

Ambient Temperature VS. Relative Intensity

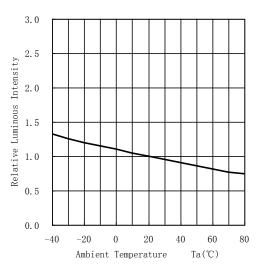
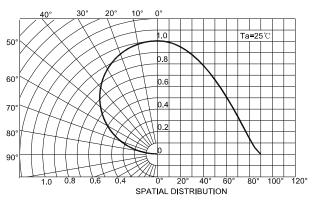


Diagram characteristics of radiation

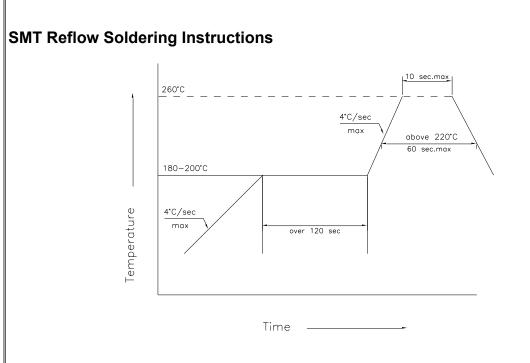


Reliability Test Items And Conditions

The reliability of products shall be satisfied with items listed below. Confidence level :90% LTPD :10%

No.	Items	Ref.Standard	Test Condition	Test Hours/ Cycles	Sample Size	Ac/Re
1	Reflow	JESD22-B106	Temp:260℃max T=10 sec	3 times.	22Pcs.	0/1
2	Temperature Cycle	JESD22-A104	100℃±5℃ 30 min. ↑↓5 min -40℃±5℃ 30 min.	100 Cycles	22Pcs.	0/1
3	Thermal Shock	JESD22-A106	100℃±5℃ 5 min. ↑↓ -40℃±5℃ 5 min.	100 Cycles	22Pcs.	0/1
4	High Temperature Storage	JESD22-A103	Temp:100℃±5℃	1000Hrs.	22Pcs.	0/1
5	Low Temperature Storage	JESD22-A119	Temp:-40℃±5℃	1000Hrs.	22Pcs.	0/1
6	DC Operating Life	JESD22-A108	Ta=25℃±5℃ IF=20mA	1000Hrs.	22Pcs.	0/1
7	High Temperature High Humidity	JESD22-A101	85℃±5℃/ 85%RH IF=5mA	1000Hrs.	22Pcs.	0/1

*The technical information shown in the data sheets are limited to the typical characteristics and circuit examples of the referenced products. It does not constitute the warranting of industrial property nor the granting of any license.



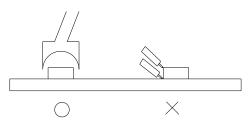
1.Reflow soldering should not be done more than two times 2.When soldering , do not put stress on the LEDs during heating

Soldering iron

1.When hand soldering, the temperature of the iron must less than 300° C for 3 seconds 2.The hand solder should be done only one times

Repairing

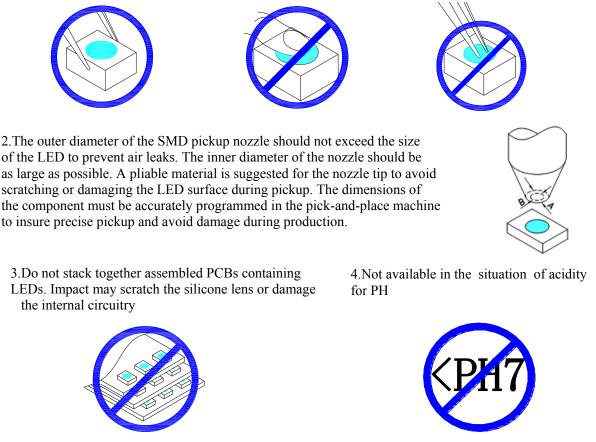
Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of LEDs will or will not be damaged by repairing.



Handling Precautions

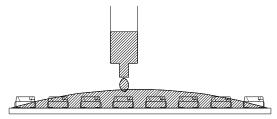
Compare to epoxy encapsulant that is hard and brittle, silicone is softer and flexible. Although its characteristic significantly reduces thermal stress, it is more susceptible to damage by external mechanical force. As a result, Special handling precautions need to be observed during assemble using silicone encapsulated LED products, Failure to comply might leads to damage and premature failure of the LED.

1.Handle the component along the side surface by using forceps or appropriate tools; do not directly touch or Handle the silicone lens surface, it may damage the internal circuitry.



5.LED operating environment and sulfur element composition cannot be over 100PPM in the LED mating

6. When we need to use external glue for LED application products, please make sure that the external glue matches the LED packaging glue. Additionally ,as most of LED packaging glue is silica gel, and it has strong Oxygen permeability as well as strong moisture permeability; in order to prevent external material from getting into the inside of LED, which may cause the malfunction of LED, the single content of Bromine element is required to be less than 900PPM, the single content of Chlorine element is required to be less than 900PPM, the single content of Chlorine element is required to be less than 900PPM.



7. Other points for attention, please refer to our LED user manual.

